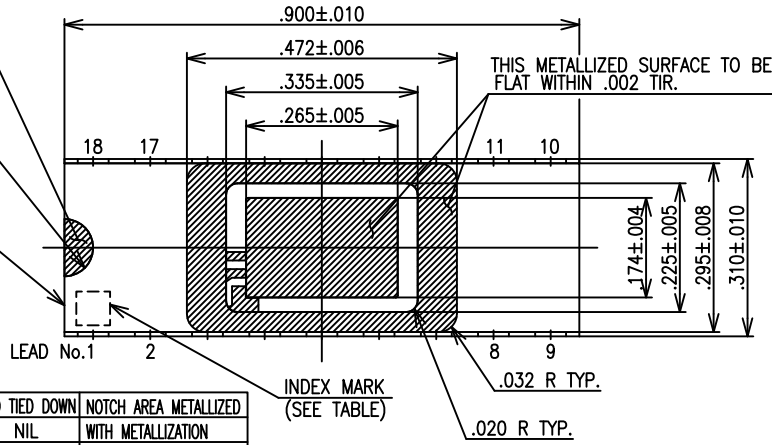


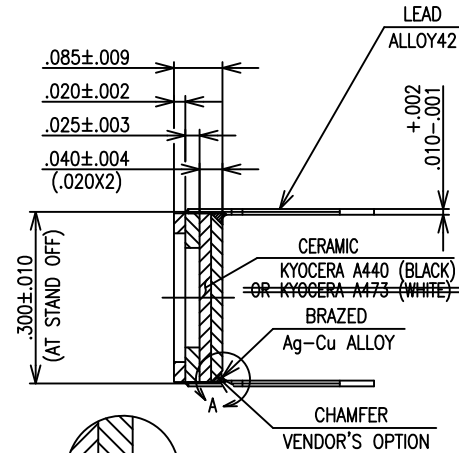
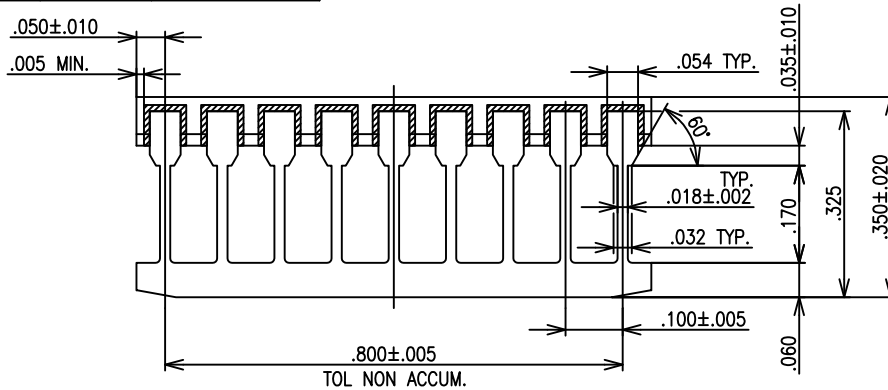
# SSM P/N: CSB01844

THIS METALLIZED AREA IS CONNECTED TO DIE ATTACH PAD (PART No.01 ONLY)

.050 R NOTCH  
GRAINDING AFTER Au PLATING. (ONLY PART No.03)



PART No.	INDEX MARK	LEAD TIED DOWN	NOTCH AREA METALLIZED
01	⊕	NIL	WITH METALLIZATION
02	⊕	NO.1 ONLY	WITH METALLIZATION
03	⊕	NIL	WITHOUT METALLIZATION



DETAIL-A

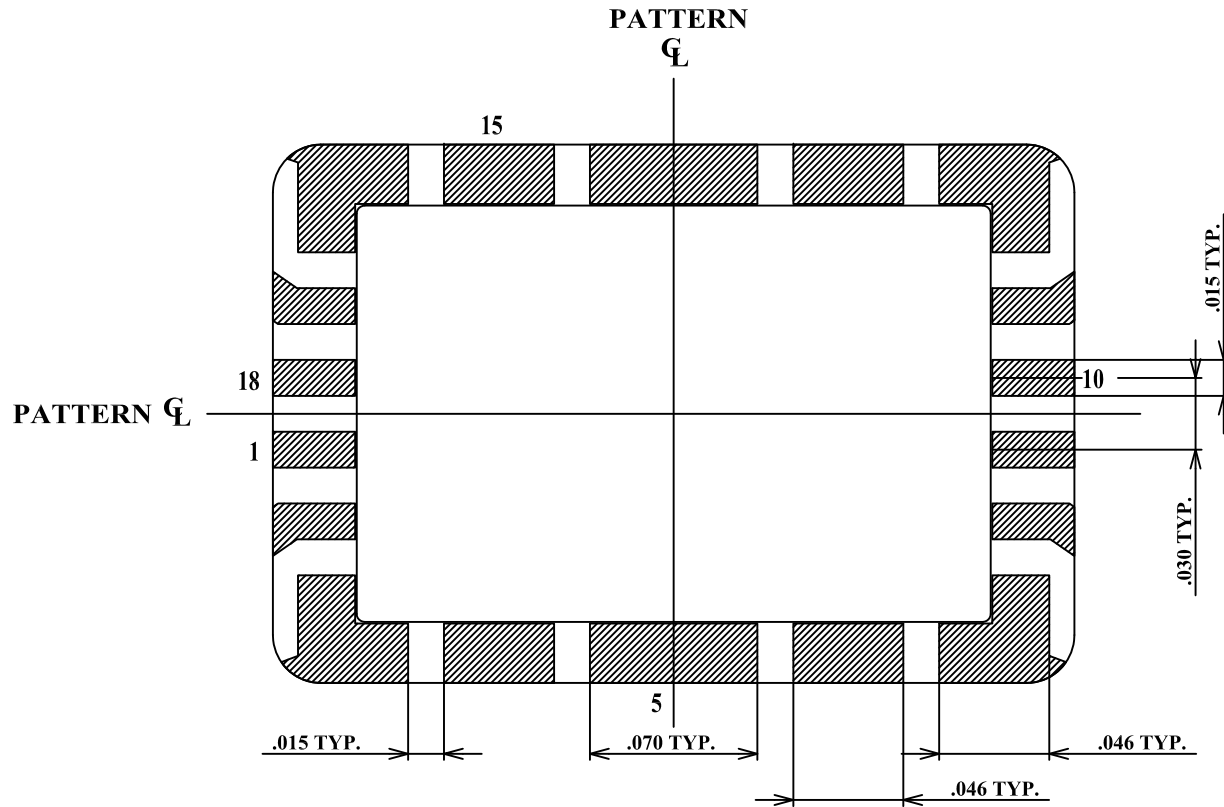
NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING TO BE FLOATING FROM ANY LEADS.
5. LEAD RESISTANCE : 0.10 OHM MAX. AT LEAD NO.9,18 OTHER LESS THAN 0.20 OHM MAX.
6. WIRE BOND PAD CONNECTED TO CORRESPONDED OUTER LEADS.
7. MISALIGNMENT OF METALLIZATION PATTERN IN CAVITY SHALL BE ACCEPTED DUE TO LAYER MISALIGNMENT.

SB018H032-3	S=0 D=0
<del>SB018H032-2</del>	<del>S=0 D=1</del>
SB018H032-1	S=0 D=0

MODIFICATION	DESCRIPTION	DATE	DRAWN	CHECKED	APPROVED	NAME	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
								M.K	K.M		FEB.18.'77
△	REDRAWN : (DELETE PART No.02 , ADDED PART No.03)	MAR.18.'70	T.M/Y.H	H.TA/S.N	Y.F	18 LEAD SIDE BRAZED PACKAGE	±.005				
△	REDRAWN: (CONVERTED CAD DATA) ADDED:SHEET 2/2	OCT.20.'94	K.I	T.C/S.F	T.A	SCALE 5 / 1	THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	<b>KYOCERA</b>		KYOCERA CORPORATION KYOTO JAPAN		DRAWING NO.	SHEET
										KD-S77032-H	1/2





**BONDING PATTERN**

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE	
						18 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	M.K	K.M		FEB.18.77	
						SCALE 20/1	MATERIAL					
							THIRD ANGLE PROJECTION					
	△	REDRAWN: (CONVERTED CAD DATA)	OCT.20.94	K.I	T.C/S.F	T.A	<b>KYOCERA</b>	KYOCERA CORPORATION KYOTO JAPAN			DRAWING NO.	SHEET
		CHANGED	DATE	DRAWN	CHECKED	APPROVED					KD-S77032-H	2/2